

ABSTRACT OF THE DISCLOSURE

A semiconductor element provided in a semiconductor device includes a built-in contact-type sensor having a sensor area formed on a circuit formation surface. Connection terminals are provided in an area other than the sensor area. A wiring board is connected to the connection terminals of the semiconductor element so that an end surface of the wiring board is positioned on the circuit formation surface. A protective resin part covers a part extending from the end surface of the wiring board to the circuit formation surface so as to protect a connection portion between the semiconductor element and the wiring board.